

## ABSTRACT OF THE DISCLOSURE

SEMICONDUCTOR DEVICE, METHOD OF MANUFACTURING THE SAME,  
CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

A semiconductor device comprising an insulating film on which a plurality of bumps and wires connected to the bumps are formed, a semiconductor chip connected to the wires and mounted to the insulating film, an epoxy resin provided in a connection portion between the semiconductor chip and the insulating film, and a radiating plate adhered to the semiconductor chip, wherein a space is formed between the insulating film and the radiating plate, and holes through which ventilation can be performed are formed in the insulating film at the positions corresponding to the space.

FIG. 1



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